ABSTRACT

DICING SYSTEM AND METHOD

A singulation system for dicing IC units from a substrate comprising; a block for receiving said substrate, said block movable from a substrate receiving station to a dicing station; a first dicing saw for dicing the substrate when at the dicing station; a second dicing saw for dicing the substrate when at the dicing station; wherein the first and second dicing saws are of different varieties so as to perform different dicing functions on said substrate.

Figure 4